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CONFIRMATION NO. 4215

Bib Data Sheet

SERIAL NUMBER 10/782,270	FILING DATE 02/18/2004	CLASS 257	GROUP ART UNIT 2815	ATTORNEY DOCKET NO. 2269-4973.1US (00-0593.01)
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APPLICANTS

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** CONTINUING DATA *****

This application is a CON of 10/150,902 05/17/2002
mbc

** FOREIGN APPLICATIONS *****

SINGAPORE 200201301-9 03/04/2002 *mbc*

IF REQUIRED, FOREIGN FILING LICENSE GRANTED

** 05/13/2004

Foreign Priority claimed	<input checked="" type="checkbox"/> yes <input type="checkbox"/> no	STATE OR COUNTRY SINGAPORE	SHEETS DRAWING 18	TOTAL CLAIMS 26	INDEPENDENT CLAIMS 2
35 USC 119 (a-d) conditions met	<input checked="" type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> Met after Allowance				
Verified and Acknowledged	<i>Yannick Lee</i> Examiner's Signature	<i>mbc</i> Initials			

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TITLE

Interposer substrate and wafer scale interposer substrate member for use with flip-chip configured semiconductor dice

FILING FEE	FEES: Authority has been given in Paper No. _____ to charge/credit DEPOSIT ACCOUNT	<input type="checkbox"/> All Fees <input type="checkbox"/> 1.16 Fees (Filing) <input type="checkbox"/> 1.17 Fees (Processing Ext. of time) <input type="checkbox"/> 1.18 Fees (Issue) <input type="checkbox"/> Other _____
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